

Amendments to the Specification

Please replace the title of the application with the following amended title:

"OFF SUBSTRATE FLIP-CHIP APPARATUS AND METHOD"

Please replace paragraph [0001] with the following amended paragraph:

[0001] The present application is related to and claims priority of prior co pending Provisional Patent Application No. 60/419,336, filed October 17, 2002 entitled "Latching Off-Chip Hinge Mechanism for Micromechanical Systems (MEMS) Components". The contents of this Provisional Patent Application are hereby incorporated by reference herein.

Please replace paragraph [0003] with the following amended paragraph:

[0003] The present document is somewhat related to the co pending and commonly assigned patent application documents "MICROMECHANICAL DEVICE LATCHING, AFD 00624, serial number 10/xxx,xxx;10/690,157 and "HINGED BONDING OF MICROMECHANICAL DEVICES" AFD 00625, serial number 10/xxx,xxx-10/690,159 that are filed of even date herewith. The contents of these somewhat related applications are hereby incorporated by reference herein."

Please replace the ABSTRACT of the application with the following amended ABSTRACT:

A flip-chip micromechanical device and process in which one module of a flip-chip device is stabilized in the substrate-free condition to a degree permitting its successful combination with a second module of the flip-chip device without the benefit of a supporting but interfering substrate element. An etch plate header and coupling tethers provide supporting rigidity to the substrate removed module during its manipulation sequence. Locking of the substrate-free module into a manipulation tolerant and manageable, even by hand, cantilevered status is included. Simplified off chip fabrication of MEMS devices in low cost facilities having only basic alignment equipment is supported by the invention.